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Docket No.: 005918 USA/FPS/MMCS/APC

PATENT/OFFICIAL

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor Application of

SHANMUGASUNDRAM et al.

Serial No. 09/943,955

Filed: August 31, 2001

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Group Art Unit: 2122
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Examiner:

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APR 28 2003

Technology Center 2100

For: FEEDBACK CONTROL OF A CHEMICAL MECHANICAL POLISHING DEVICE
PROVIDING MANIPULATION OF REMOVAL RATE PROFILES

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Honorable Commissioner for Patents
Washington, D.C. 20231

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Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

This submission does not constitute a representation that a search has been made or that no better art exists and does not constitute an admission or representation that any of the listed documents is material or constitutes prior art. If it should be determined that any of the listed documents does not constitute prior art under the United States law, Applicants reserve the right

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to present to the Office the relevant facts and law regarding the appropriate status of such document.

No certification or fee is believed to be required. However, the Commissioner is hereby authorized to charge any additional fees should any be required for this submission, or credit any overpayment to deposit account no. 08-0219.

Respectfully submitted,

HALE AND DORR LLP



Scott M. Alter

Registration No. 32,879

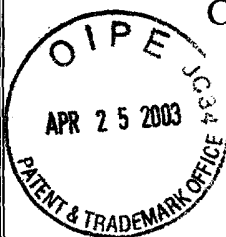
1455 Pennsylvania Avenue, NW
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Date: 4/25/03

INFORMATION DISCLOSURE
CITATION IN AN
APPLICATION
(PTO-1449)



ATTY. DOCKET NO.
005918
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APPLICANT
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	4,000,458	12/28/76	Miller et al.			08/21/75
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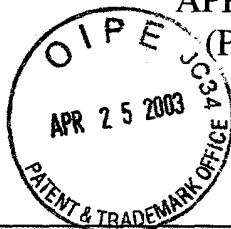
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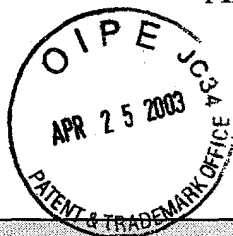
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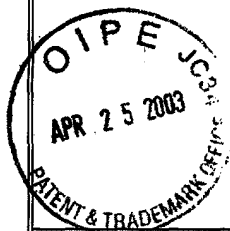
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						Yes	No
	61-66104	04/04/86	Japan			X	
	3-202710	09/04/91	Japan			X	
	8-23166	01/23/96	Japan			X	
	9-246547	09/19/97	Japan			X	
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	10-34522	02/10/98	Japan			X	
	0 869 652	10/07/98	Europe			X	
	WO 99/09371	02/25/99	WIPO			X	
	0 910 123	04/21/99	Europe			X	
	0 932 194	07/28/99	Europe			X	
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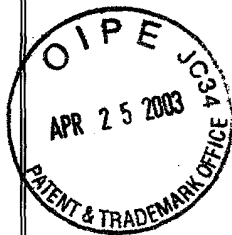
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						Yes	No
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	WO 01/25865	04/12/01	WIPO			X	
	434103	05/16/01	Taiwan			X	
	436383	05/28/01	Taiwan			X	
	455938	09/21/01	Taiwan			X	
	455976	09/21/01	Taiwan			X	
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<p align="center">INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)</p> <p align="center">O I P E APR 25 2003 PATENT & TRADEMARK OFFICE</p>	<p>ATTY. DOCKET NO. 005918 USA/FPS/MMC/STAPC</p> <p align="center">RECEIVED JUL 24 2003 GROUP 170</p>	<p>SERIAL NO. 09/943,955</p> <p align="center">RECEIVED APR 28 2003</p>
	<p>APPLICANT SHANMUGASUNDRAM et al. Technology Center 2100</p>	
	<p>FILING DATE August 31, 2001</p>	<p>GROUP 2122</p>
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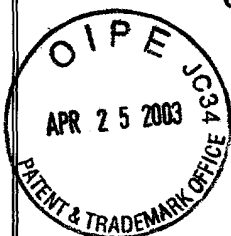
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